


APPLICABLE STANDARD					
RATING	OPERATING TEMPERATURE RANGE	-40 °C TO +85 °C(NOTE1) 	STORAGE TEMPERATURE RANGE	-10 °C TO +60 °C(NOTE2)	
	OPERATING HUMIDITY RANGE	40 % TO 80 %(NOTE3)	STORAGE HUMIDITY RANGE	40 % TO 70 % (NOTE2)	
	VOLTAGE	AC 250 V	UL · CSA VOLTAGE	AC 30V	
	CURRENT	2A	RATING CURRENT	2A	

SPECIFICATIONS

ITEM	TEST METHOD	REQUIREMENTS	QT	AT
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CONSTRUCTION

GENERAL EXAMINATION	VISUALLY AND BY MEASURING INSTRUMENT.	ACCORDING TO DRAWING.	x	x
MARKING	CONFIRMED VISUALLY.		x	x

ELECTRIC CHARACTERISTICS


CONTACT RESISTANCE	100 mA (DC OR 1000 Hz).	30 mΩ MAX.	x	—
INSULATION RESISTANCE	500 V DC.	1000 MΩ MIN.	x	—
VOLTAGE PROOF	650 V AC FOR 1 min.	NO FLASHOVER OR BREAKDOWN.	x	—

MECHANICAL CHARACTERISTICS

MECHANICAL OPERATION	50 TIMES INSERTIONS AND EXTRACTIONS.	① CONTACT RESISTANCE: 30 mΩ MAX. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	x	—
VIBRATION	FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.	① NO ELECTRICAL DISCONTINUITY OF 1μs. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	x	—
SHOCK	490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.	① NO ELECTRICAL DISCONTINUITY OF 1μs. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	x	—


ENVIRONMENTAL CHARACTERISTICS

DAMP HEAT (STEADY STATE)	EXPOSED AT 40±2 °C, 90 TO 95 %, 96 h.	① CONTACT RESISTANCE: 30 mΩ MAX. ② INSULATION RESISTANCE: 500 MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	x	—
RAPID CHANGE OF TEMPERATURE	TEMPERATURE -55 →5 TO 35→85 →5 TO 35 °C TIME 30 →10 TO 15→10→15 TO 3 min UNDER 5 CYCLES.	① CONTACT RESISTANCE: 30 mΩ MAX. ② INSULATION RESISTANCE: 1000MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	x	—
RESISTANCE TO SOLDERING HEAT	1)AUTOMATIC SOLDERING (FLOW) SOLDER TEMPERATURE : 260°C FOR IMMERSION,DURATION , 10 sec . 2)MANUAL SOLDERING SOLDERING IRON TEMPERATURE : 300°C SOLDERING TIME : 2 sec. NO STRENGTH ON CONTACT.	NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.	x	—
SOLDERABILITY	SOLDERED AT SOLDER TEMPERATURE,230°C FOR IMMERSION DURATION,3 sec.	SOLDER SHALL COVER A MINIMUM OF 95% OF THE SURFACE BEING IMMERSED	x	—

	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
	1	DIS-H-008540	MI. SAKIMURA	HK. UMEHARA	14.02.26

REMARKS NOTE1:INCLUDE THE TEMPERATURE RISING BY CURRENT. NOTE2:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD. AFTER PCB BOARD,OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERIM STORAGE DURING TRANSPORTATION. NOTE3:NON-CONDENSING. Unless otherwise specified, refer to IEC 60512.	APPROVED	KJ. KATAYOSE	05.01.05
	CHECKED	TY. OMA	05.01.05
	DESIGNED	IO. DENPOUYA	05.01.05
	DRAWN	IO. DENPOUYA	05.01.05

Note QT:Qualification Test AT:Assurance Test X:Applicable Test	DRAWING NO.	ELC4-080551-01
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HRS	SPECIFICATION SHEET	PART NO.	DF11-*DP-2DSA (01)		
	HIROSE ELECTRIC CO., LTD.	CODE NO.	CL543		1/1